MOSFETs Silicon N-Channel MOS (DTMOSIV-H)

TK31E60X

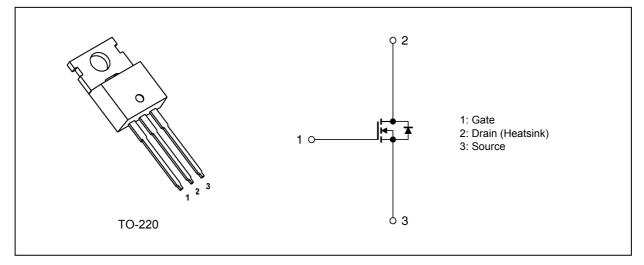
1. Applications

Switching Voltage Regulators

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 0.073 \Omega$ (typ.) by used to Super Junction Structure : DTMOS
- (2) High-speed switching properties with lower capacitance.
- (3) Enhancement mode: V_{th} = 2.5 to 3.5 V (V_{DS} = 10 V, I_D = 1.5 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V
Gate-source voltage		V _{GSS}	±30	
Drain current (DC)	(Note 1)	I _D	30.8	Α
Drain current (pulsed)	(Note 1)	I _{DP}	123	
Power dissipation (T	_c = 25°C)	PD	230	W
Single-pulse avalanche energy	(Note 2)	E _{AS}	437	mJ
Avalanche current		I _{AR}	7.7	Α
Reverse drain current (DC)	(Note 1)	I _{DR}	30.8	
Reverse drain current (pulsed)	(Note 1)	I _{DRP}	123	
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150	7
Mounting torque		TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

5. Thermal Characteristics

Characteristics		Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	0.543	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	83.3	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 12.9 mH, R_G = 25 Ω , I_{AR} = 7.7 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V	_	_	±1	μA
Drain cut-off current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	600	—	—	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1.5 mA	2.5	_	3.5	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 9.4 A		0.073	0.088	Ω

6.2. Dynamic Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V_{DS} = 300 V, V_{GS} = 0 V, f = 100 kHz		3000	_	pF
Reverse transfer capacitance	C _{rss}]		7	_	
Output capacitance	C _{oss}	1	_	70	_	
Effective output capacitance	C _{o(er)}	V_{DS} = 0 to 400 V, V_{GS} = 0 V	_	123	_	
Gate resistance	r _g	V _{DS} = OPEN, f = 1 MHz	_	1.8	_	Ω
Switching time (rise time)	tr	See Figure 6.2.1		22		ns
Switching time (turn-on time)	t _{on}	1		55	_	
Switching time (fall time)	t _f			6	_	
Switching time (turn-off time)	t _{off}	1		130	_	
MOSFET dv/dt ruggedness	dv/dt	V _{DD} = 0 to 400 V, I _D = 7.7 A	50	_	_	V/ns

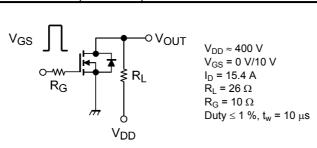


Fig. 6.2.1 Switching Time Test Circuit

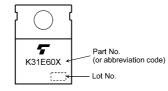
6.3. Gate Charge Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 400 \text{ V}, \text{ V}_{GS}$ = 10 V, I _D = 30.8 A	_	65	_	nC
Gate-source charge 1	Q _{gs1}		_	19	_	
Gate-drain charge	Q _{gd}			22	_	

6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

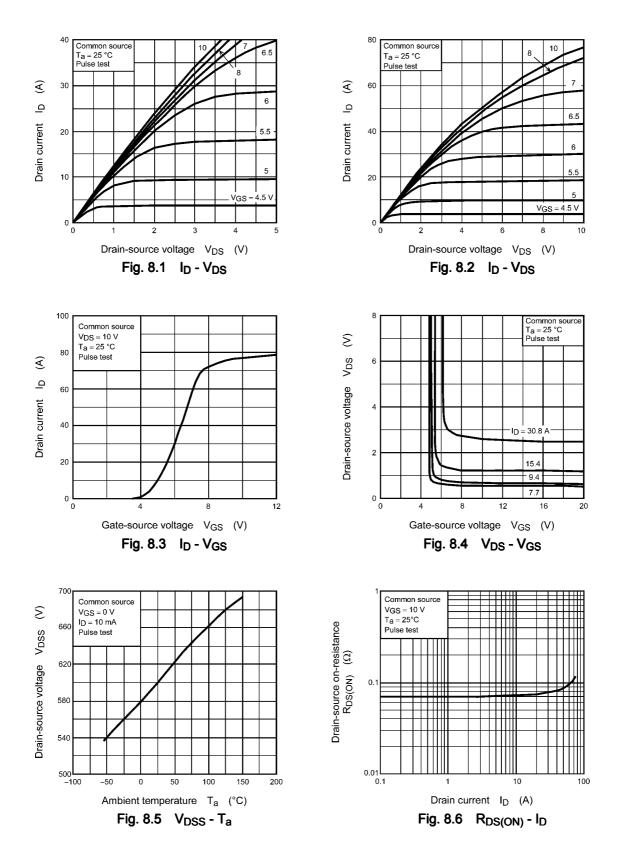
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	V _{DSF}	I _{DR} = 30.8 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 15.4 A, V _{GS} = 0 V	_	410	_	ns
Reverse recovery charge	Q _{rr}	-dI _{DR} /dt = 50 A/μs	_	3.5	_	μC
Peak reverse recovery current	I _{rr}		_	17	_	А
Diode dv/dt ruggedness	dv/dt	I_{DR} = 15.4 A, V_{GS} = 0 V, V_{DD} = 400 V	15	_	_	V/ns

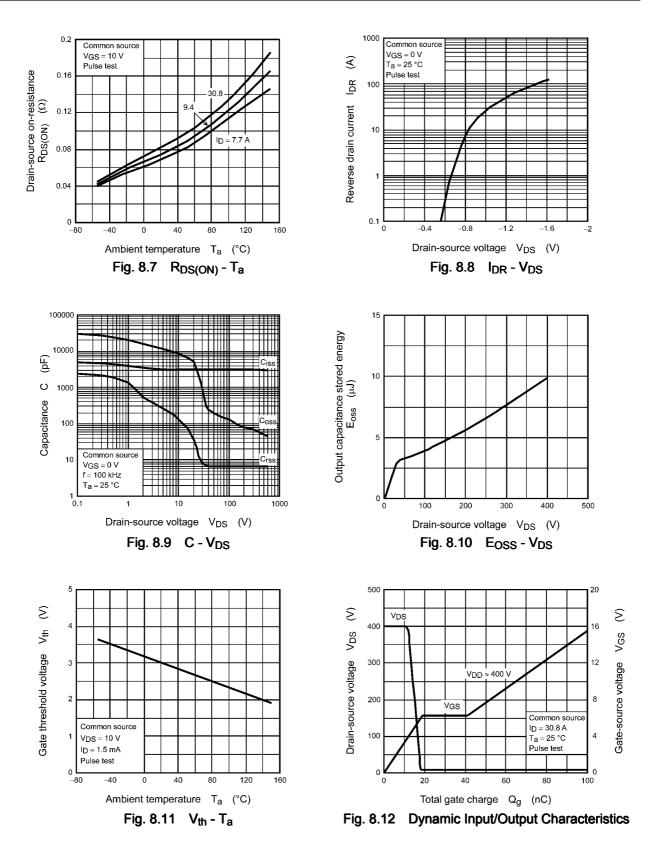
7. Marking





8. Characteristics Curves (Note)





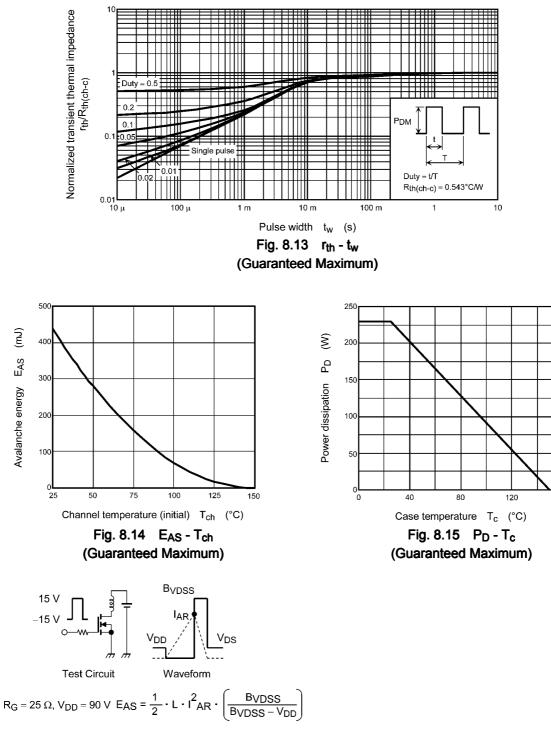
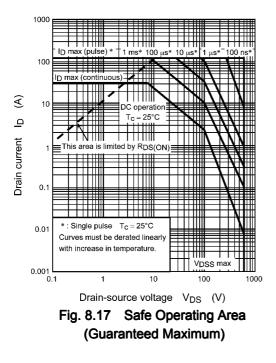


Fig. 8.16 Test Circuit/Waveform

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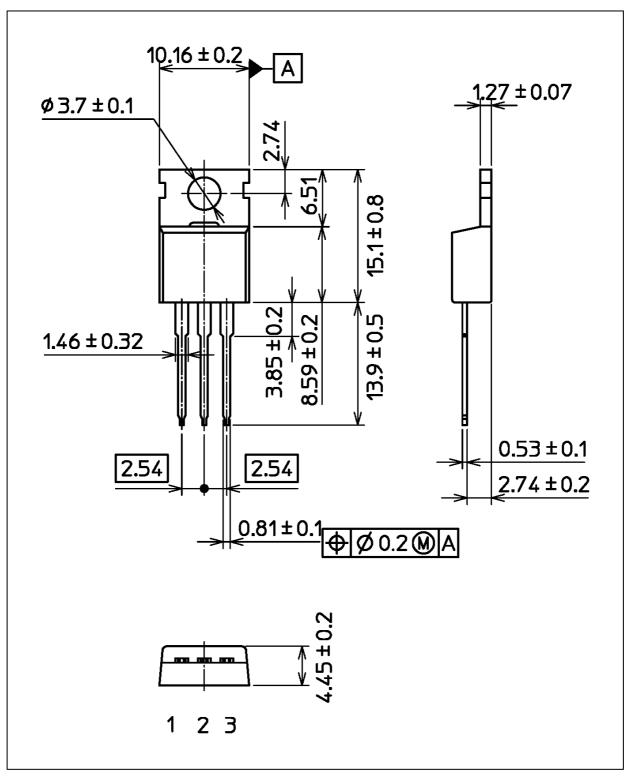


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

TK31E60X

Unit: mm



Weight: 1.93 g (typ.)

	Package Name(s)
TOSHIBA: 2-10X1A	
Nickname: TO-220	

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